IN THE SPECIFICATION:

Please replace the paragraph beginning on page 7, line 3 with the following paragraph:

Solder 5 is applied to the inner surface of the lid 1 on at least ~~the portion of~~ the lip 4. In order to further increase the strength and airtightness of a solder joint between the lid 1 and the base K, solder 5 is preferably applied to the entire inner surface of the lid 1. When the lid 1 is disposed on a plate-shaped base K and the two are heated, if solder 5 is applied to the entire inner surface of the lid 1, the solder 5 present between the lip 4 and the base K melts, and the solder 5 which was applied to the inner surface of the top portion 2 and the side walls 3 simultaneously melts. At this time, the molten solder between the lip 4 and the base K pulls the molten solder on the top portion 2 and the side walls 3 downwards, and a large amount of molten solder 5 accumulates in the vicinity of the lip 4 to create a joint between the lid 1 and the base K over a larger area. As a result, the strength and the airtightness of the solder joint are both increased.

Please replace the paragraph beginning on page 8, line 31 with the following paragraph:

First, as shown in Figure 5A, a metal strip 6 made of a suitable material, such as Kovar, and having a layer of solder 5 applied to one side thereof is prepared. The solder 5 can be applied to the metal strip 6 by a variety of methods, including

cladding, in which the metal strip 6 and a strip of solder 5 are together passed through rollers and mechanically bonded to each other, and a molten solder method, i.e., hot dipping, in which one side of the metal strip 6 is brought into contact with molten solder to plate the surface with solder. Of these two methods, the molten solder (hot dipping) method is preferred, since cladding causes work hardening of the strip 6, which makes subsequent drawing operations more difficult.

Please replace the paragraph beginning on page 9, line 30 with the following paragraph:

To demonstrate the effectiveness of a lid according to the present invention, a Pb-rich high temperature solder was applied by ~~a~~ the molten solder (hot dipping) method on one side of a Kovar strip having a thickness of 100 μm to form a ~~plated~~ hot-dipped solder layer with a thickness of 20 μm. The ~~solder plated~~ resulting strip was then subjected to drawing in the manner shown in Figure 5B with a series of dies to form recessed shapes each having a rectangular top portion measuring 2.4 x 1.9 mm and having a depth of 0.4 mm. The solder layer ~~is~~ was on the interior of the recessed shapes. The recessed shapes were then punched out of the strip with a punching press in the manner shown in Figure 5C to obtain lids having a lip at the lower ends of the side walls of the lid and projecting from the outer surfaces of the side walls by 100 μm.